

## FEATURES

- Low Forward Voltage Drop
- Fast Switching
- Small Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- Available in Lead Free Version

## MECHANICAL DATA

- \* Case: Molded plastic
- \* Epoxy: UL 94V-0 rate flame retardant
- \* Terminals: Solder plated, solderable per MIL-STD-202F method 208 guaranteed
- \* Polarity: Color band denotes cathode end
- \* Mounting position: Any



VOLTAGE RANGE  
30 Volts  
CURRENT  
0.2 Ampere

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.  
Single phase half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Parameter	Symbol	Limit	Unit
DC blocking voltage	$V_R$	30	V
RMS reverse voltage	$V_{R(RMS)}$	21	V
Average rectified output current	$I_o$	100	mA
Forward continuous current	$I_F$	200	mA
Repetitive peak forward current	$I_{FRM}$	300	mA
Non-repetitive Peak Forward Surge Current @ $t=8.3ms$	$I_{FSM}$	600	mA
Power dissipation	$P_d$	500	mW
Thermal resistance junction to ambient	$R_{\theta JA}$	200	°C/W
Operating Junction Temperature Range	$T_J$	-40 ~ +125	°C
Storage Temperature Range	$T_{STG}$	-55 ~ +150	°C

### Electrical Characteristics (T<sub>A</sub> = 25 °C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse breakdown voltage	$V_{(BR)}$	$I_R=100\mu A$	30			V
Forward voltage	$V_{F1}$	$I_F=0.1mA$			240	mV
	$V_{F2}$	$I_F=1.0mA$			320	mV
	$V_{F3}$	$I_F=10mA$			400	mV
	$V_{F4}$	$I_F=30mA$			500	mV
	$V_{F5}$	$I_F=100mA$			1000	mV
Reverse current	$I_R$	$V_R=25V$			2.0	uA
Reverse recovery time	$t_{rr}$	$I_F=10mA, I_R=10mA$ to 1mA, $R_L=100\Omega$			5.0	ns
Capacitance between terminals	$C_T$	$V_R=1V, f=1MHz$			10	pF

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

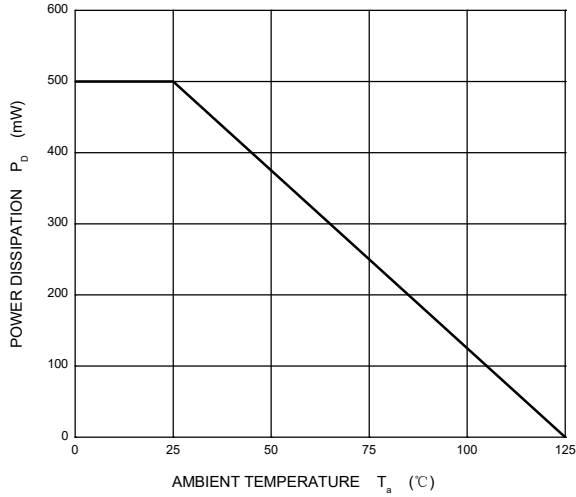


FIG.2-TYPICAL FORWARD CHARACTERISTICS

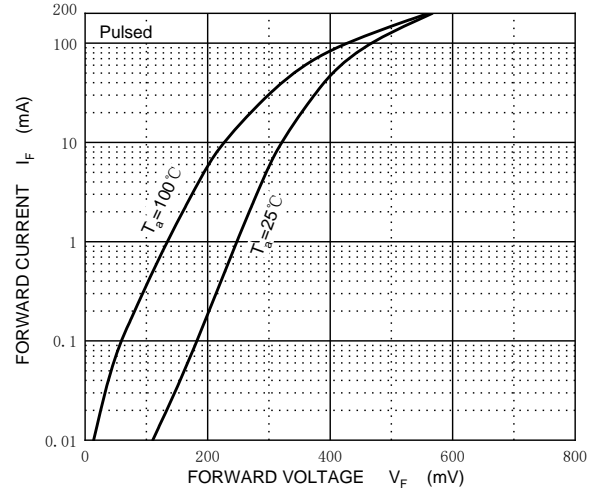


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

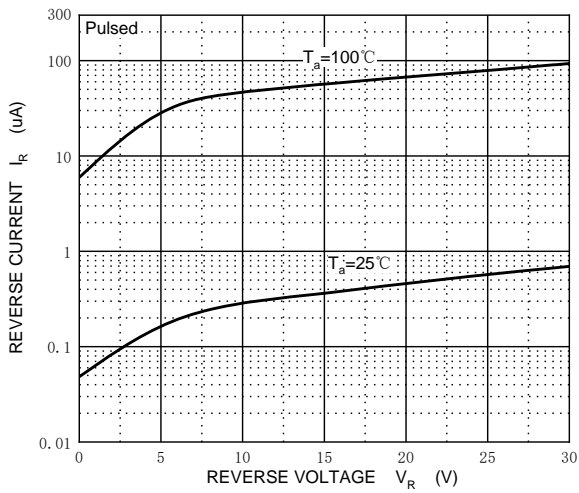
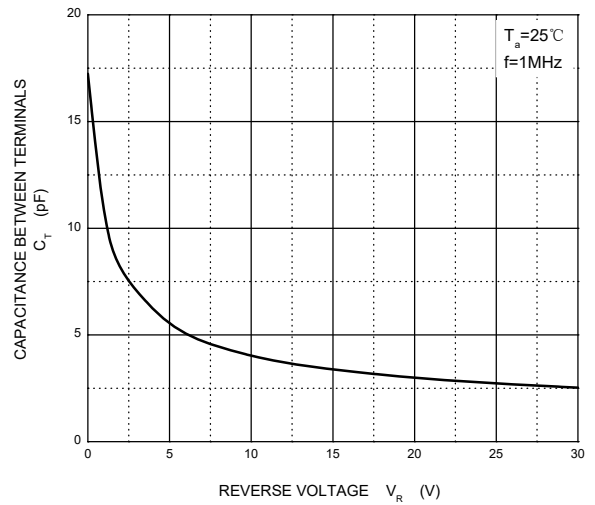
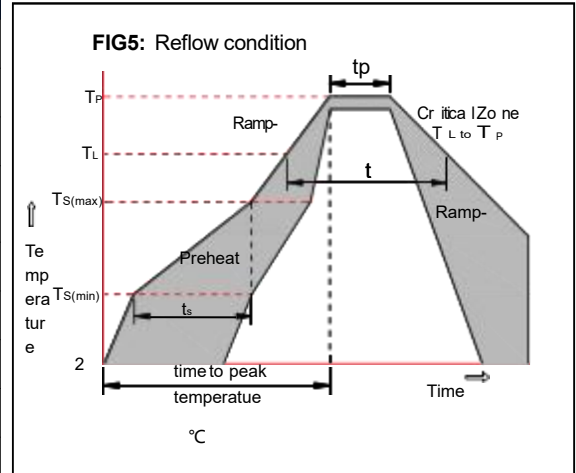


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT



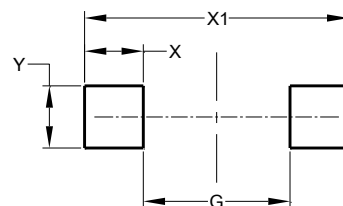
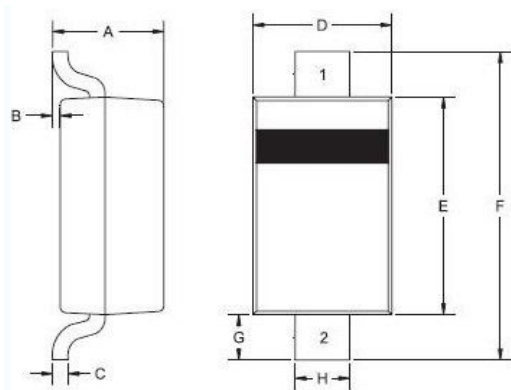
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150 °C
	-Temperature Max( $T_{s(max)}$ )	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3 °C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature( $T_L$ )(Liquid us)	+217 °C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_P$ )		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260 °C



Package Dimensions & Suggested Pad Layout

SOD123



SOD123		
Dim	Min	Max
A	0.95	1.35
B	0.00	0.12
C	-	0.20
D	1.40	1.80
E	2.50	2.80
F	3.60	3.90
G	0.40	-
H	0.50	0.70
All Dimensions in mm		

Dimensions	Value (in mm)
G	2.20
X	1.20
X1	4.60
Y	1.20

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.20
		P1	4.00±0.20
		P2	2.00±0.20
		D0	1.55±0.10
		D1	1.00±0.20
		E	1.75±0.20
		F	3.60±0.20
		W	8.00±0.40
		A0	2.30±0.40
		B0	4.00±0.40
		K0	1.50±0.40
		T	0.23±0.10
		D2	177.0±3.0
		D3	55Min.
		D4	R24.0±3.0
G	R82.0±3.0		
I	13.0±2.0		
W1	11.0±3.0		
Quantity: 3000PCS			

7" Reel

